

NBSG14

2.5V/3.3V SiGe Differential 1:4 Clock/Data Driver with RSECL* Outputs

*Reduced Swing ECL

Description

The NBSG14 is a 1-to-4 clock/data distribution chip, optimized for ultra-low skew and jitter.

Inputs incorporate internal 50 Ω termination resistors and accept NECL (Negative ECL), PECL (Positive ECL), LVTTTL, LVCMOS, CML, or LVDS. Outputs are RSECL (Reduced Swing ECL), 400 mV.

Features

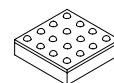
- Maximum Input Clock Frequency up to 12 GHz Typical
- Maximum Input Data Rate up to 12 Gb/s Typical
- 30 ps Typical Rise and Fall Times
- 125 ps Typical Propagation Delay
- RSPECL Output with Operating Range: $V_{CC} = 2.375$ V to 3.465 V with $V_{EE} = 0$ V
- RSNECL Output with RSNECL or NECL Inputs with Operating Range: $V_{CC} = 0$ V with $V_{EE} = -2.375$ V to -3.465 V
- RSECL Output Level (400 mV Peak-to-Peak Output), Differential Output
- 50 Ω Internal Input Termination Resistors
- Compatible with Existing 2.5 V/3.3 V LVEP, EP, and LVEL Devices
- Pb-Free Packages are Available



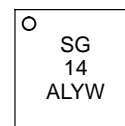
ON Semiconductor®

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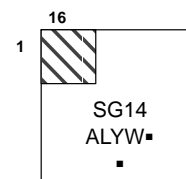
MARKING DIAGRAMS*



FCBGA-16
BA SUFFIX
CASE 489



QFN-16
MN SUFFIX
CASE 485G



A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
■ = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 11 of this data sheet.

NBSG14

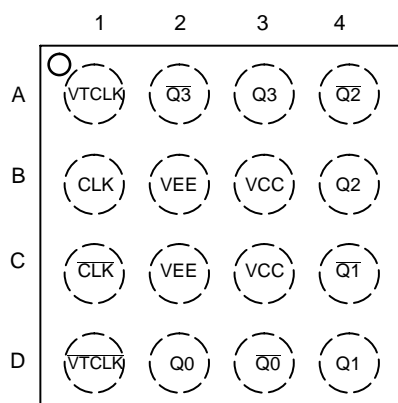


Figure 1. BGA-16 Pinout (Top View)

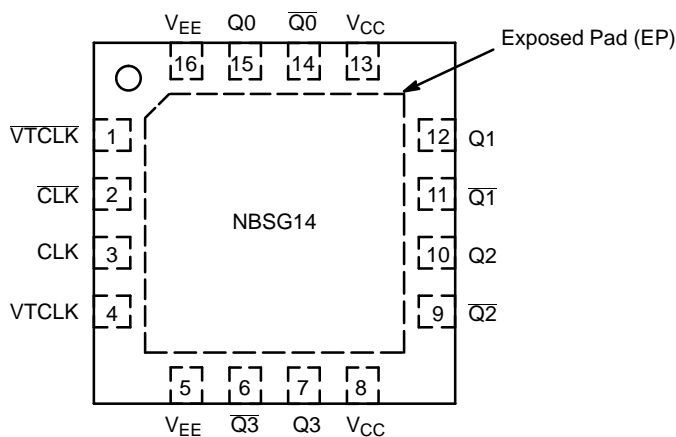


Figure 2. QFN-16 Pinout (Top View)

Table 1. Pin Description

| Pin | | Name | I/O | Description |
|-------|------|-----------------|--------------------------------------|---|
| BGA | QFN | | | |
| D1 | 1 | VTCLK | – | Internal 50 Ω Termination pin. See Table 2. |
| C1 | 2 | CLK | ECL, CML, LVCMOS, LVDS, LVTTTL Input | Inverted Differential Input. Internal 75 k Ω to V_{EE} and 36.5 k Ω to V_{CC} . |
| B1 | 3 | CLK | ECL, CML, LVCMOS, LVDS, LVTTTL Input | Noninverted Differential Input. Internal 75 k Ω to V_{EE} . |
| A1 | 4 | VTCLK | – | Internal 50 Ω Termination Pin. See Table 2. |
| B2,C2 | 5,16 | V_{EE} | – | Negative Supply Voltage. All V_{EE} Pins must be Externally Connected to Power Supply to Guarantee Proper Operation. |
| A2* | 6 | $\overline{Q3}$ | RSECL Output | Inverted Differential Output 3. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2 V^*$ |
| A3* | 7 | Q3 | RSECL Output | Noninverted Differential Output 3. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2 V^*$ |
| B3,C3 | 8,13 | V_{CC} | – | Positive Supply Voltage. All V_{CC} Pins must be Externally Connected to Power Supply to Guarantee Proper Operation. |
| A4* | 9 | $\overline{Q2}$ | RSECL Output | Inverted Differential Output 2. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2 V^*$ |
| B4* | 10 | Q2 | RSECL Output | Noninverted Differential Output 2. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2 V^*$ |
| C4* | 11 | $\overline{Q1}$ | RSECL Output | Inverted Differential Output 1. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2 V^*$ |
| D4* | 12 | Q1 | RSECL Output | Noninverted Differential Output 1. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2 V^*$ |
| D3* | 14 | $\overline{Q0}$ | RSECL Output | Inverted Differential Output 0. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2 V^*$ |
| D2* | 15 | Q0 | RSECL Output | Noninverted Differential Output 0. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2 V^*$ |
| N/A | – | EP | – | Exposed Pad. The thermally exposed pad on package bottom (see case drawing) must be attached to a heat-sinking conduit. |

1. In the differential configuration when the input termination pins (VTCLK, \overline{VTCLK}) are connected to a common termination voltage, if no signal is applied then the device will be susceptible to self-oscillation.

*Devices in BGA package typically terminated with 50 Ω to $V_{TT} = V_{CC} - 1.5 V$.

NBSG14

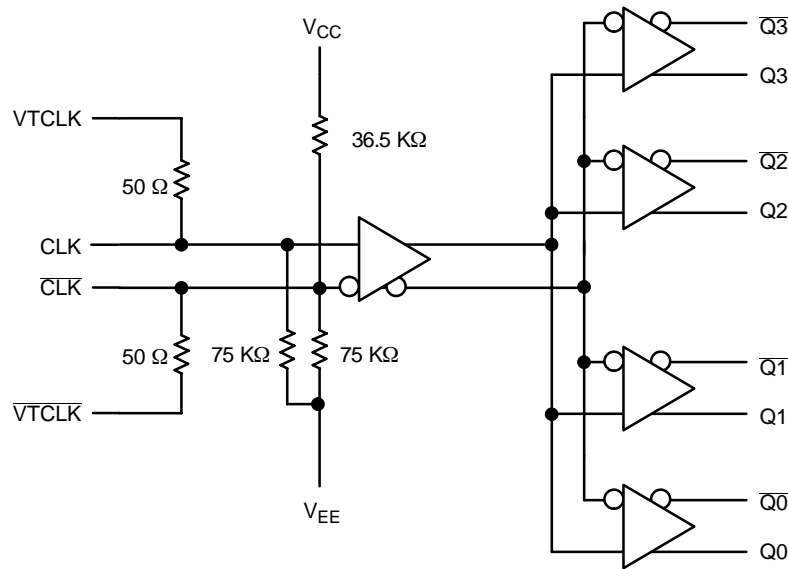


Figure 3. Logic Diagram

Table 2. INTERFACING OPTIONS

| INTERFACING OPTIONS | CONNECTIONS |
|---------------------|---|
| CML | Connect VTCLK and $\overline{\text{VTCLK}}$ to VCC |
| LVDS | Connect VTCLK and $\overline{\text{VTCLK}}$ Together |
| AC-COUPLED | Bias VTCLK and $\overline{\text{VTCLK}}$ Inputs within Common Mode Range (V_{IHCMR}) |
| RSECL, PECL, NECL | Standard ECL Termination Techniques |
| LVTTL, LVCMOS | An External Voltage (V_{THR}) should be Applied to the Unused Differential Input. Nominal V_{THR} is 1.5 V for LVTTL and $V_{\text{CC}}/2$ for LVCMOS Inputs. This Voltage must be within the V_{THR} Specification. |

Table 3. ATTRIBUTES

| Characteristics | Value | Value |
|--|------------------------|----------------------|
| Internal Input Pulldown Resistor (CLK, $\overline{\text{CLK}}$) | 75 k Ω | |
| Internal Input Pullup Resistor ($\overline{\text{CLK}}$) | 36.5 k Ω | |
| ESD Protection | Human Body Model | > 2 kV |
| | Machine Model | > 100 V |
| Moisture Sensitivity (Note 1) | Pb Pkg | Pb-Free Pkg |
| | FCBGA-16 | Level 3 |
| | QFN-16 | Level 1 |
| Flammability Rating | Oxygen Index: 28 to 34 | UL 94 V-0 @ 0.125 in |
| Transistor Count | 158 | |
| Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test | | |

1. For additional information, see Application Note AND8003/D.

NBSG14

Table 4. MAXIMUM RATINGS

| Symbol | Parameter | Condition 1 | Condition 2 | Rating | Unit |
|---------------|--|---|--|---------------------------|------------------------------|
| V_{CC} | Positive Power Supply | $V_{EE} = 0\text{ V}$ | | 3.6 | V |
| V_{EE} | Negative Power Supply | $V_{CC} = 0\text{ V}$ | | -3.6 | V |
| V_I | Positive Input Negative Input | $V_{EE} = 0\text{ V}$ $V_{CC} = 0\text{ V}$ | $V_I \leq V_{CC}$ $V_I \geq V_{EE}$ | 3.6 -3.6 | V V |
| V_{INPP} | Differential Input Voltage CLK-CLK | $V_{CC} - V_{EE} \geq 2.8\text{ V}$ $V_{CC} - V_{EE} < 2.8\text{ V}$ | | 2.8 $V_{CC}-V_{EE}$ | V |
| I_{IN} | Input Current Through R_T (50 Ω Resistor) | Static Surge | | 45 80 | mA mA |
| I_{OUT} | Output Current | Continuous Surge | | 25 50 | mA mA |
| T_A | Operating Temperature Range | 16 FCBGA 16 QFN | | -40 to +70 -40 to +85 | °C |
| T_{stg} | Storage Temperature Range | | | -65 to +150 | °C |
| θ_{JA} | Thermal Resistance (Junction-to-Ambient) (Note 2) | 0 lfpm 500 lfpm 0 lfpm 500 lfpm | 16 FCBGA 16 FCBGA 16 QFN 16 QFN | 108 86 41.6 35.2 | °C/W °C/W °C/W °C/W |
| θ_{JC} | Thermal Resistance (Junction-to-Case) | 2S2P (Note 2) 2S2P (Note 3) | 16 FCBGA 16 QFN | 5 4.0 | °C/W °C/W |
| T_{sol} | Wave Solder Pb Pb-Free | | | 225 225 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

2. JEDEC standard 51-6, multilayer board – 2S2P (2 signal, 2 power).

3. JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 5. DC CHARACTERISTICS, INPUT WITH RSPECL OUTPUT $V_{CC} = 2.5\text{ V}$; $V_{EE} = 0\text{ V}$ (Note 4)

| Symbol | Characteristic | -40°C | | | 25°C | | | 70°C(BGA)/85°C(QFN)** | | | Unit |
|-------------|--|-----------------|-------------------|----------------|-----------------|-------------------|----------------|-----------------------|-------------------|----------------|---------------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| I_{EE} | Negative Power Supply Current | 45 | 60 | 75 | 45 | 60 | 75 | 45 | 60 | 75 | mA |
| V_{OH} | Output HIGH Voltage (Note 5) | 1525 | 1575 | 1625 | 1550 | 1610 | 1650 | 1575 | 1635 | 1675 | mV |
| V_{OUTPP} | Output Amplitude Voltage | 315 | 405 | 495 | 315 | 405 | 495 | 315 | 405 | 495 | mV |
| V_{IH} | Input HIGH Voltage (Single-Ended) (Notes 7 and 9) | $V_{CC} - 1435$ | $V_{CC} - 1000^*$ | V_{CC} | $V_{CC} - 1435$ | $V_{CC} - 1000^*$ | V_{CC} | $V_{CC} - 1435$ | $V_{CC} - 1000^*$ | V_{CC} | mV |
| V_{IL} | Input LOW Voltage (Single-Ended) (Notes 8 and 9) | $V_{IH} - 2500$ | $V_{CC} - 1400^*$ | $V_{IH} - 150$ | $V_{IH} - 2500$ | $V_{CC} - 1400^*$ | $V_{IH} - 150$ | $V_{IH} - 2500$ | $V_{CC} - 1400^*$ | $V_{IH} - 150$ | mV |
| V_{THR} | Input Threshold Voltage (Single-Ended) (Note 9) | $V_{EE} + 1125$ | | $V_{CC} - 75$ | $V_{EE} + 1125$ | | $V_{CC} - 75$ | $V_{EE} + 1125$ | | $V_{CC} - 75$ | mV |
| V_{IHCMR} | Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 6) | 1.2 | | 2.5 | 1.2 | | 2.5 | 1.2 | | 2.5 | V |
| R_{TIN} | Internal Input Termination Resistor | 45 | 50 | 55 | 45 | 50 | 55 | 45 | 50 | 55 | Ω |
| I_{IH} | Input HIGH Current (@ V_{IH}) | | 80 | 150 | | 80 | 150 | | 80 | 150 | μA |
| I_{IL} | Input LOW Current (@ V_{IL}) | | 25 | 100 | | 25 | 100 | | 25 | 100 | μA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

*Typicals used for testing purposes.

**The device packaged in FCBGA-16 have maximum temperature specification of 70°C and devices packaged in QFN-16 have maximum temperature specification of 85°C.

4. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.125 V to -0.5 V.

5. All outputs loaded with 50 Ω to $V_{CC} - 1.5\text{ V}$ for BGA package and $V_{CC} - 2\text{ V}$ for QFN package. V_{OH}/V_{OL} measured at V_{IH}/V_{IL} (Typical).

6. V_{IHCMR} min varies 1:1 with V_{EE} ; V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

7. V_{IH} cannot exceed V_{CC} . $|V_{IH} - V_{THR}| < 2600\text{ mV}$.

8. V_{IL} always $\geq V_{EE}$. $|V_{IL} - V_{THR}| < 2600\text{ mV}$.

9. V_{THR} is the voltage applied to one input when running in single-ended mode.

Table 6. DC CHARACTERISTICS, INPUT WITH RSPECL OUTPUT $V_{CC} = 3.3\text{ V}$; $V_{EE} = 0\text{ V}$ (Note 10)

| Symbol | Characteristic | -40°C | | | 25°C | | | 70°C(BGA)/85°C(QFN)** | | | Unit |
|-------------|---|-----------------|-------------------|----------------|-----------------|-------------------|----------------|-----------------------|-------------------|----------------|---------------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| I_{EE} | Negative Power Supply Current | 45 | 60 | 75 | 45 | 60 | 75 | 45 | 60 | 75 | mA |
| V_{OH} | Output HIGH Voltage (Note 11) | 2325 | 2375 | 2425 | 2350 | 2410 | 2450 | 2375 | 2435 | 2475 | mV |
| V_{OUTPP} | Output Amplitude Voltage | 350 | 440 | 530 | 350 | 440 | 530 | 350 | 440 | 530 | mV |
| V_{IH} | Input HIGH Voltage (Single-Ended) (Notes 13 and 15) | $V_{CC} - 1435$ | $V_{CC} - 1000^*$ | V_{CC} | $V_{CC} - 1435$ | $V_{CC} - 1000^*$ | V_{CC} | $V_{CC} - 1435$ | $V_{CC} - 1000^*$ | V_{CC} | mV |
| V_{IL} | Input LOW Voltage (Single-Ended) (Notes 14 and 15) | $V_{IH} - 2500$ | $V_{CC} - 1400^*$ | $V_{IH} - 150$ | $V_{IH} - 2500$ | $V_{CC} - 1400^*$ | $V_{IH} - 150$ | $V_{IH} - 2500$ | $V_{CC} - 1400^*$ | $V_{IH} - 150$ | mV |
| V_{THR} | Input Threshold Voltage (Single-Ended) (Note 15) | $V_{EE} + 1125$ | | $V_{CC} - 75$ | $V_{EE} + 1125$ | | $V_{CC} - 75$ | $V_{EE} + 1125$ | | $V_{CC} - 75$ | mV |
| V_{IHCMR} | Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 12) | 1.2 | | 3.3 | 1.2 | | 3.3 | 1.2 | | 3.3 | V |
| R_{TIN} | Internal Input Termination Resistor | 45 | 50 | 55 | 45 | 50 | 55 | 45 | 50 | 55 | Ω |
| I_{IH} | Input HIGH Current (@ V_{IH}) | | 80 | 150 | | 80 | 150 | | 80 | 150 | μA |
| I_{IL} | Input LOW Current (@ V_{IL}) | | 25 | 100 | | 25 | 100 | | 25 | 100 | μA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

*Typicals used for testing purposes.

**The device packaged in FCBGA-16 have maximum temperature specification of 70°C and devices packaged in QFN-16 have maximum temperature specification of 85°C.

10. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.3 V to -0.165 V.

11. All outputs loaded with 50 Ω to $V_{CC} - 1.5\text{ V}$ for BGA package and $V_{CC} - 2\text{ V}$ for QFN package. V_{OH}/V_{OL} measured at V_{IH}/V_{IL} (Typical).

12. V_{IHCMR} min varies 1:1 with V_{EE} ; V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

13. V_{IH} cannot exceed V_{CC} . $|V_{IH} - V_{THR}| < 2600\text{ mV}$.

14. V_{IL} always $\geq V_{EE}$. $|V_{IL} - V_{THR}| < 2600\text{ mV}$.

15. V_{THR} is the voltage applied to one input when running in single-ended mode.

Table 7. DC CHARACTERISTICS, NECL OR RSNECL INPUT WITH NECL OUTPUT

$V_{CC} = 0\text{ V}$; $V_{EE} = -3.465\text{ V}$ to -2.375 V (Note 16)

| Symbol | Characteristic | -40°C | | | 25°C | | | 70°C(BGA)/85°C(QFN)** | | | Unit |
|-------------|---|-----------------|-----------------|--------------|-----------------|-----------------|--------------|-----------------------|-----------------|--------------|---------------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| I_{EE} | Negative Power Supply Current | 45 | 60 | 75 | 45 | 60 | 75 | 45 | 60 | 75 | mA |
| V_{OH} | Output HIGH Voltage (Note 17) | -975 | -925 | -875 | -950 | -890 | -850 | -925 | -865 | -825 | mV |
| V_{OUTPP} | Output Amplitude Voltage $-3.465\text{ V} \leq V_{EE} \leq -3.0\text{ V}$ $-3.0\text{ V} < V_{EE} \leq -2.375\text{ V}$ | 350 315 | 440 405 | 530 495 | 350 315 | 440 405 | 530 495 | 350 315 | 440 405 | 530 495 | mV |
| V_{IH} | Input HIGH Voltage (Single-Ended) (Notes 19 and 21) | $V_{CC}-1435$ | $V_{CC}-1000^*$ | V_{CC} | $V_{CC}-1435$ | $V_{CC}-1000^*$ | V_{CC} | $V_{CC}-1435$ | $V_{CC}-1000^*$ | V_{CC} | mV |
| V_{IL} | Input LOW Voltage (Single-Ended) (Notes 20 and 21) | $V_{IH}-2500$ | $V_{CC}-1400^*$ | $V_{IH}-150$ | $V_{IH}-2500$ | $V_{CC}-1400^*$ | $V_{IH}-150$ | $V_{IH}-2500$ | $V_{CC}-1400^*$ | $V_{IH}-150$ | mV |
| V_{THR} | Input Threshold Voltage (Single-Ended) (Note 21) | $V_{EE} + 1125$ | | $V_{CC}-75$ | $V_{EE} + 1125$ | | $V_{CC}-75$ | $V_{EE} + 1125$ | | $V_{CC}-75$ | mV |
| V_{IHCMR} | Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 18) | $V_{EE} + 1.2$ | | 0.0 | $V_{EE} + 1.2$ | | 0.0 | $V_{EE} + 1.2$ | | 0.0 | V |
| R_{TIN} | Internal Input Termination Resistor | 45 | 50 | 55 | 45 | 50 | 55 | 45 | 50 | 55 | Ω |
| I_{IH} | Input HIGH Current (@ V_{IH}) | | 80 | 150 | | 80 | 150 | | 80 | 150 | μA |
| I_{IL} | Input LOW Current (@ V_{IL}) | | 25 | 100 | | 25 | 100 | | 25 | 100 | μA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

*Typicals used for testing purposes.

**The device packaged in FCBGA-16 have maximum temperature specification of 70°C and devices packaged in QFN-16 have maximum temperature specification of 85°C.

16. Input and output parameters vary 1:1 with V_{CC} .

17. All outputs loaded with 50 Ω to $V_{CC} - 1.5\text{ V}$ for BGA package and $V_{CC} - 2\text{ V}$ for QFN package. V_{OH}/V_{OL} measured at V_{IH}/V_{IL} (Typical).

18. V_{IHCMR} min varies 1:1 with V_{EE} , V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

19. V_{IH} cannot exceed V_{CC} . $|V_{IH} - V_{THR}| < 2600\text{ mV}$.

20. V_{IL} always $\geq V_{EE}$. $|V_{IL} - V_{THR}| < 2600\text{ mV}$.

21. V_{THR} is the voltage applied to one input when running in single-ended mode.

Table 8. AC CHARACTERISTICS for FCBGA-16

$V_{CC} = 0\text{ V}$; $V_{EE} = -3.465\text{ V}$ to -2.375 V or $V_{CC} = 2.375\text{ V}$ to 3.465 V ; $V_{EE} = 0\text{ V}$

| Symbol | Characteristic | -40°C | | | 25°C | | | 70°C | | | Unit |
|--------------------------|---|-------|--------------|----------------|------|--------------|----------------|------|--------------|----------------|------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| f_{\max} | Maximum Frequency (See Figure 4) (Note 22) | 10.7 | 12 | | 10.7 | 12 | | 10.7 | 12 | | GHz |
| t_{PLH} , t_{PHL} | Propagation Delay to Output Differential | 100 | 125 | 150 | 100 | 125 | 150 | 100 | 125 | 150 | ps |
| t_{SKEW} | Duty Cycle Skew (Note 23) Within-Device Skew (Note 24) Device-to-Device Skew (Note 25) | | 2 6 25 | 10 15 50 | | 2 6 25 | 10 15 50 | | 2 6 25 | 10 15 50 | ps |
| t_{JITTER} | RMS Random Clock Jitter (Figure 4) (Note 27) $f_{in} < 10\text{ GHz}$ Peak-to-Peak Data Dependent Jitter (Note 28) $f_{in} < 10\text{ Gb/s}$ | | 0.2 | 1 | | 0.2 10 | 1 | | 0.2 | 1 | ps |
| V_{INPP} | Input Voltage Swing/Sensitivity (Differential Configuration) (Note 26) | 75 | | 2600 | 75 | | 2600 | 75 | | 2600 | mV |
| t_r t_f | Output Rise/Fall Times Q, \bar{Q} (20% – 80%) @ 1 GHz | 20 | 30 | 55 | 20 | 30 | 55 | 20 | 30 | 55 | ps |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

22. Measured using a 500 mV source, 50% duty cycle clock source. All outputs loaded with $50\ \Omega$ to $V_{CC} - 1.5\text{ V}$. Input edge rates 40 ps (20% – 80%).

23. See Figure 6. $t_{SKEW} = |t_{PLH} - t_{PHL}|$ for a nominal 50% Differential Clock Input Waveform.

24. Within-Device skew is measured between outputs under identical transitions and conditions on any one device.

25. Device-to-device skew for identical transitions at identical V_{CC} levels.

26. V_{INPP} (MAX) cannot exceed $V_{CC} - V_{EE}$ (applicable only when $V_{CC} - V_{EE} < 2600\text{ mV}$).

27. Additive RMS Jitter with 50% duty cycle clock signal at 10 GHz.

28. Additive Peak-to-Peak data dependent jitter with NRZ PRBS $2^{31}-1$ data at 10 Gb/s.

Table 9. AC CHARACTERISTICS for QFN-16

$V_{CC} = 0\text{ V}$; $V_{EE} = -3.465\text{ V}$ to -2.375 V or $V_{CC} = 2.375\text{ V}$ to 3.465 V ; $V_{EE} = 0\text{ V}$

| Symbol | Characteristic | -40°C | | | 25°C | | | 85°C | | | Unit |
|--------------------------|---|-------|--------------|----------------|------|--------------|----------------|------|--------------|----------------|------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| f_{\max} | Maximum Frequency (See Figure 4) (Note 29) | 10.5 | 12 | | 10.5 | 12 | | 10.5 | 12 | | GHz |
| t_{PLH} , t_{PHL} | Propagation Delay to Output Differential | 90 | 125 | 160 | 90 | 125 | 160 | 90 | 125 | 160 | ps |
| t_{SKEW} | Duty Cycle Skew (Note 30) Within-Device Skew (Note 31) Device-to-Device Skew (Note 32) | | 3 6 25 | 15 15 50 | | 3 6 25 | 15 15 50 | | 3 6 25 | 15 15 50 | ps |
| t_{JITTER} | RMS Random Clock Jitter (Figure 4) (Note 34) $f_{in} < 10\text{ GHz}$ Peak-to-Peak Data Dependent Jitter (Note 35) $f_{in} < 10\text{ Gb/s}$ | | 0.2 | 1 | | 0.2 10 | 1 | | 0.2 | 1 | ps |
| V_{INPP} | Input Voltage Swing/Sensitivity (Differential Configuration) (Note 33) | 75 | | 2600 | 75 | | 2600 | 75 | | 2600 | mV |
| t_r t_f | Output Rise/Fall Times Q, \bar{Q} (20% – 80%) @ 1 GHz | 15 | 30 | 55 | 20 | 30 | 55 | 20 | 30 | 55 | ps |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

29. Measured using a 500 mV source, 50% duty cycle clock source. All outputs loaded with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$. Input edge rates 40 ps (20% – 80%)

30. See Figure 6. $t_{SKEW} = |t_{PLH} - t_{PHL}|$ for a nominal 50% Differential Clock Input Waveform.

31. Within-Device skew is measured between outputs under identical transitions and conditions on any one device.

32. Device-to-device skew for identical transitions at identical V_{CC} levels.

33. V_{INPP} (MAX) cannot exceed $V_{CC} - V_{EE}$ (applicable only when $V_{CC} - V_{EE} < 2600\text{ mV}$).

34. Additive RMS Jitter with 50% duty cycle clock signal at 10 GHz.

35. Additive Peak-to-Peak data dependent jitter with NRZ PRBS $2^{31}-1$ data at 10 Gb/s.

NBSG14

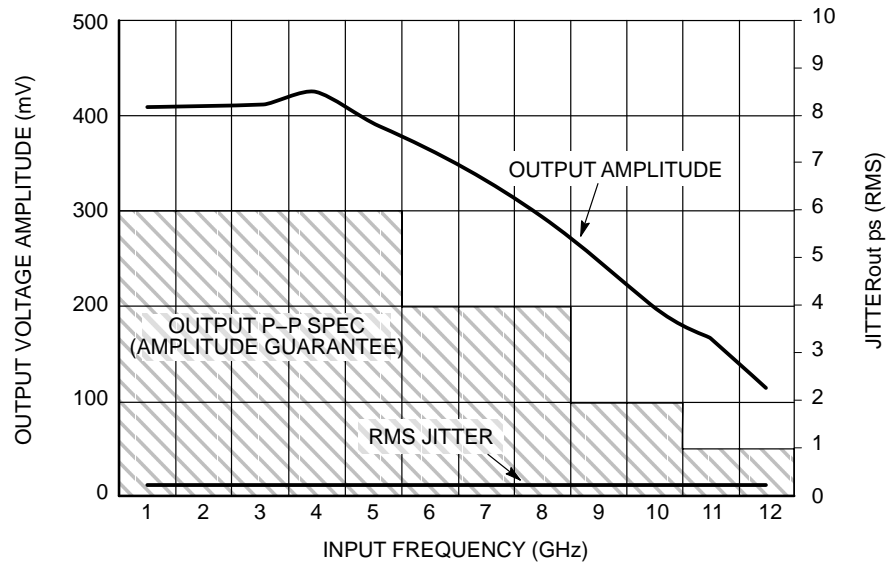
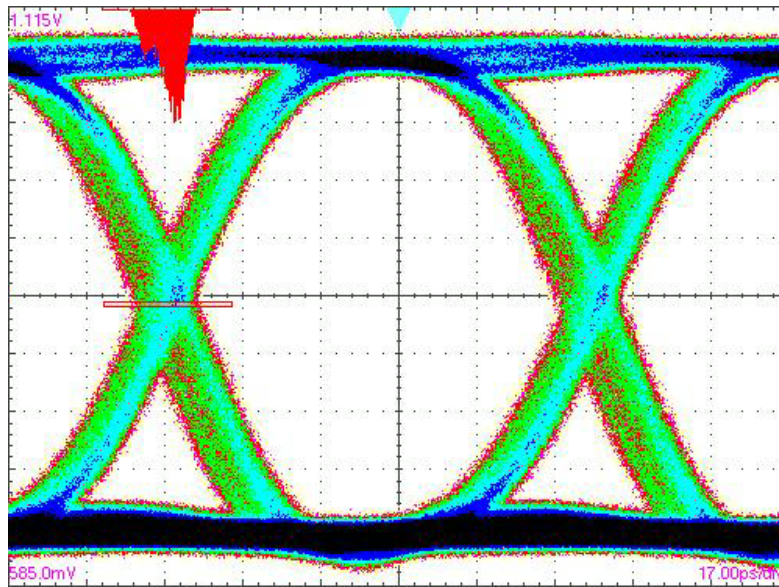


Figure 4. Output Voltage Amplitude (V_{OUTPP}) / RMS Jitter vs. Input Frequency (f_{in}) at Ambient Temperature (Typical)



X = 17 ps/DIV, Y = 53 mV/DIV

Figure 5. Eye Diagram at 10.8 Gbps
 ($V_{CC} - V_{EE} = 3.3 \text{ V}$ @ 25°C with Input Data Pattern of $2^{31}-1$ PRBS.
 Total Pk-Pk System Jitter Including Signal Generator is 18 ps.
 This Data was taken by Acquiring 7000 Waveforms.)

NBSG14

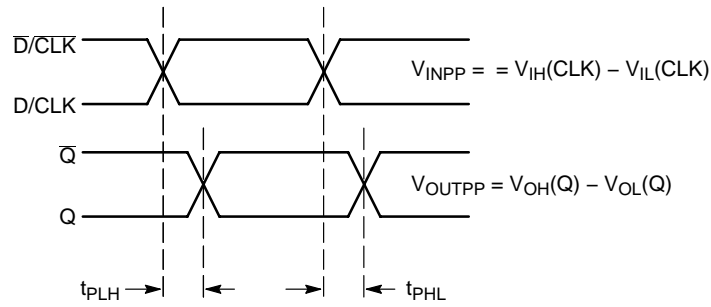


Figure 6. AC Reference Measurement

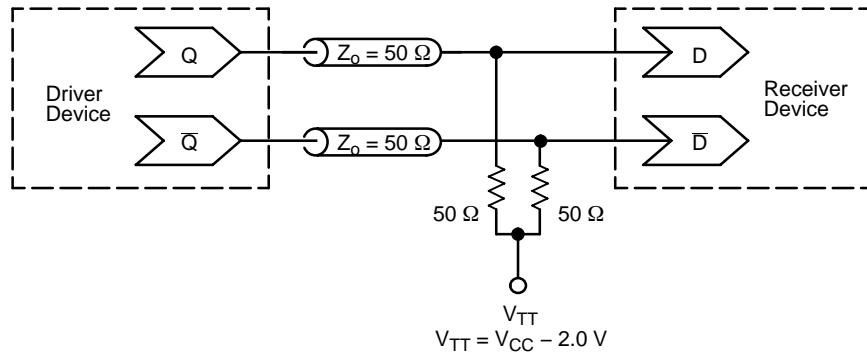


Figure 7. Typical Termination for Output Driver and Device Evaluation
(See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|-------------|---------------------|---|
| NBSG14BA | FCBGA-16 | 100 Units / Tray (Contact Sales Representative) |
| NBSG14BAR2 | FCBGA-16 | 100 / Tape & Reel |
| NBSG14MN | QFN-16 | 123 Units / Rail |
| NBSG14MNG | QFN-16 (Pb-Free) | 123 Units / Rail |
| NBSG14MNR2 | QFN-16 | 3000 / Tape & Reel |
| NBSG14MNR2G | QFN-16 (Pb-Free) | 3000 / Tape & Reel |

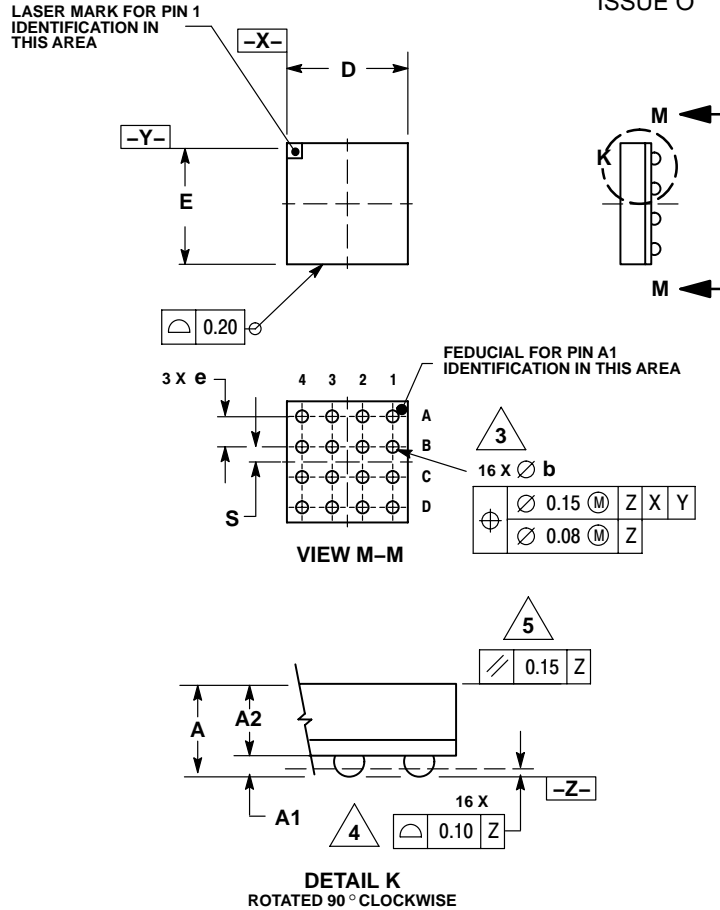
| Board | Description |
|-------------|---------------------------|
| NBSG14BAEVB | NBSG14BA Evaluation Board |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NBSG14

PACKAGE DIMENSIONS

FCBGA-16
BA SUFFIX
 PLASTIC 4X4 (mm) BGA FLIP CHIP PACKAGE
 CASE 489-01
 ISSUE O



NOTES:

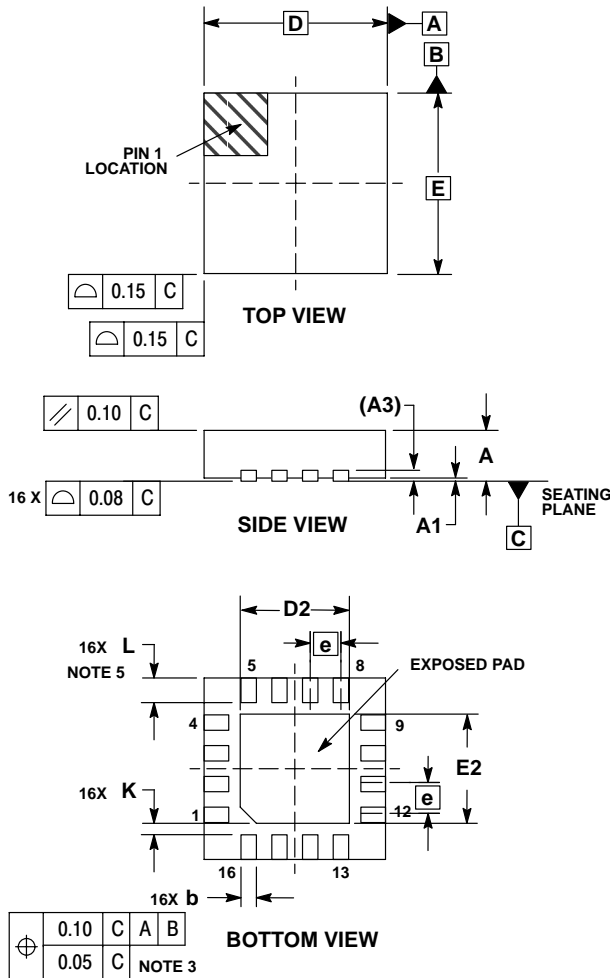
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE Z.
4. DATUM Z (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

| DIM | MILLIMETERS | |
|-----|-------------|------|
| | MIN | MAX |
| A | 1.40 | MAX |
| A1 | 0.25 | 0.35 |
| A2 | 1.20 | REF |
| b | 0.30 | 0.50 |
| D | 4.00 | BSC |
| E | 4.00 | BSC |
| e | 1.00 | BSC |
| S | 0.50 | BSC |

NBSG14

PACKAGE DIMENSIONS

16 PIN QFN CASE 485G-01 ISSUE C

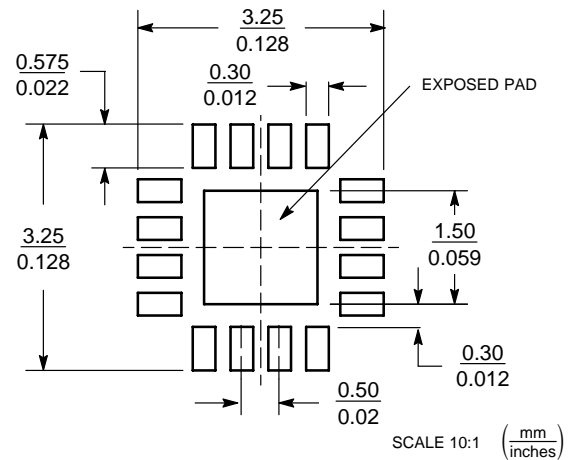


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. L_{max} CONDITION CAN NOT VIOLATE 0.2 MM MINIMUM SPACING BETWEEN LEAD TIP AND FLAG

| DIM | MILLIMETERS | |
|-----|-------------|------|
| | MIN | MAX |
| A | 0.80 | 1.00 |
| A1 | 0.00 | 0.05 |
| A3 | 0.20 REF | |
| b | 0.18 | 0.30 |
| D | 3.00 BSC | |
| D2 | 1.65 | 1.85 |
| E | 3.00 BSC | |
| E2 | 1.65 | 1.85 |
| e | 0.50 BSC | |
| K | 0.18 TYP | |
| L | 0.30 | 0.50 |

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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